

N-Channel 100 V (D-S) MOSFET

PRODUCT SUMMARY

V_{DS} (V)	$R_{DS(on)}$ (m Ω)(Typ.)	I_D (A) ^a	Q_g (Typ.)
100	11 at $V_{GS} = 10$ V	48	21.3 nC
	15 at $V_{GS} = 4.5$ V		

FEATURES

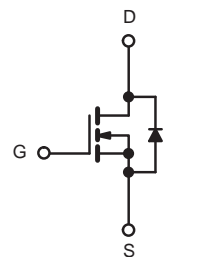
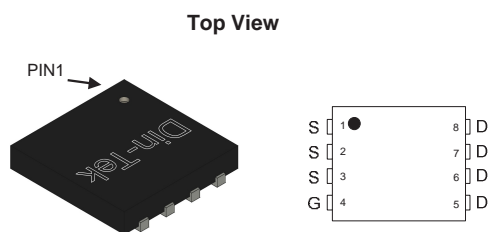
- DT-Trench Power MOSFET
- 100 % R_g and UIS Tested
- Low Gate Charge
- Logic Level Driven


RoHS
 COMPLIANT

APPLICATIONS

- AC-DC/DC-DC Converter
- Cell Phone Quick Charger

PDFN3.3X3.3-8L Pin Configuration



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^\circ\text{C}$, unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current ($T_J = 150^\circ\text{C}$) ^a	I_D	48	A
		36.5	
Pulsed Drain Current ^b	I_{DM}	178	
Single Avalanche Energy	E_{AS}	175	mJ
Maximum Power Dissipation ^c	P_D	84	W
		32.1	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to + 150	$^\circ\text{C}$

THERMAL RESISTANCE RATINGS

PARAMETER	SYMBOL	LIMIT	UNIT
Junction-to-Ambient (PCB Mount) ^d	R_{thJA}	22	$^\circ\text{C/W}$
Junction-to-Case (Drain)	R_{thJC}	1.78	

Notes

- Calculated continuous current based on maximum allowable junction temperature.
- Repetitive rating; pulse width limited by max. junction temperature.
- P_D is based on max. junction temperature, using junction-case thermal resistance.
- The value of R_{thJA} is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_a = 25^\circ\text{C}$.

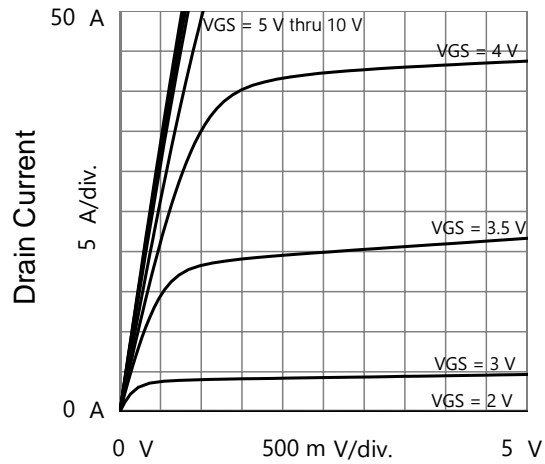
SPECIFICATIONS (T _C = 25 °C, unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	100	-	-	V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	1	-	3	
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 20 V	-	-	± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 100V, V _{GS} = 0 V	-	-	1	μA
		V _{DS} = 80 V, V _{GS} = 0 V, T _J = 125 °C	-	-	100	
On-State Drain Current ^a	I _{D(on)}	V _{DS} ≥ 5 V, V _{GS} = 10 V	48	-	-	A
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 10 V, I _D = 10 A	-	11	15	mΩ
		V _{GS} = 4.5 V, I _D = 8 A	-	15	23	
Forward Transconductance ^a	g _{fs}	V _{DS} = 5 V, I _D = 10 A	-	35	-	S
Dynamic ^b						
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 50 V, f = 1 MHz	-	1320	-	pF
Output Capacitance	C _{oss}		-	348	-	
Reverse Transfer Capacitance	C _{rss}		-	5	-	
Total Gate Charge ^c	Q _g	V _{DS} = 50 V, V _{GS} = 10 V, I _D = 10 A	-	21.3	-	nC
Gate-Source Charge ^c	Q _{gs}		-	3.05	-	
Gate-Drain Charge ^c	Q _{gd}		-	3.9	-	
Gate Resistance	R _g	f = 1 MHz	-	1.3	-	Ω
Turn-On Delay Time ^c	t _{d(on)}	V _{DD} = 50 V, I _D = 10 A, R _g = 2 Ω V _{GS} = 10 V	-	12	-	ns
Rise Time ^c	t _r		-	8	-	
Turn-Off Delay Time ^c	t _{d(off)}		-	30	-	
Fall Time ^c	t _f		-	6	-	
Drain-Source Body Diode Ratings and Characteristics ^b (T _C = 25 °C)						
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C	-	-	48	A
Pulsed Current	I _{SM}		-	-	178	A
Forward Voltage ^a	V _{SD}	I _F = 1 A, V _{GS} = 0 V	-	-	1.2	V
Reverse Recovery Time	t _{rr}	I _F = 10 A, di/dt = 100 A/μs	-	25	-	ns
Reverse Recovery Charge	Q _{rr}		-	90	-	nC

Notes

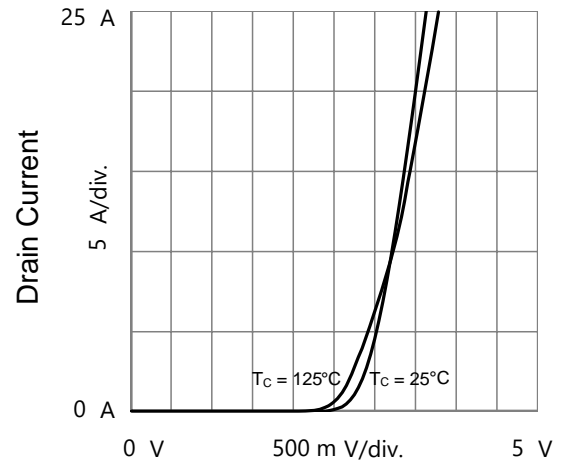
- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.
 b. Guaranteed by design, not subject to production testing.
 c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

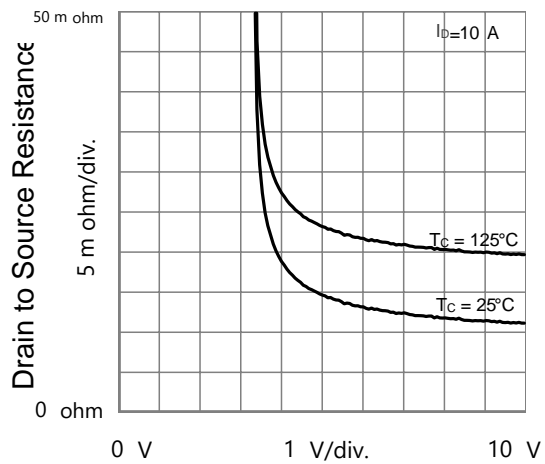
TYPICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$, unless otherwise noted)



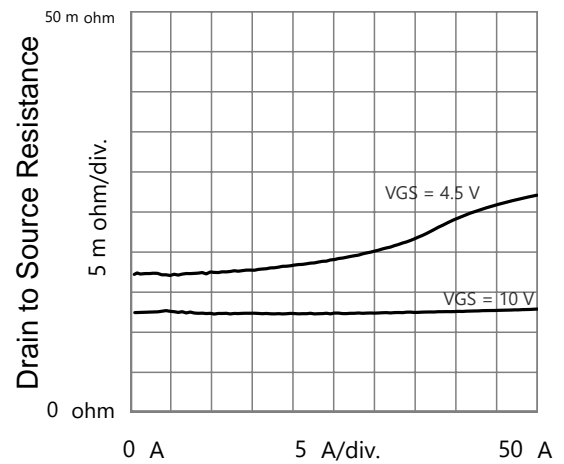
**Drain to Source Voltage
Output Characteristics**



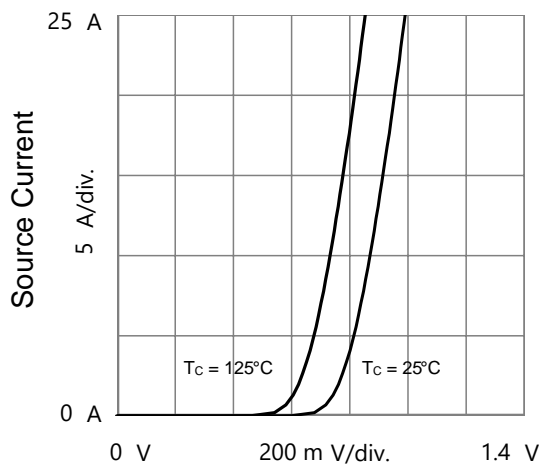
**Gate to Source Voltage
Transfer Characteristics**



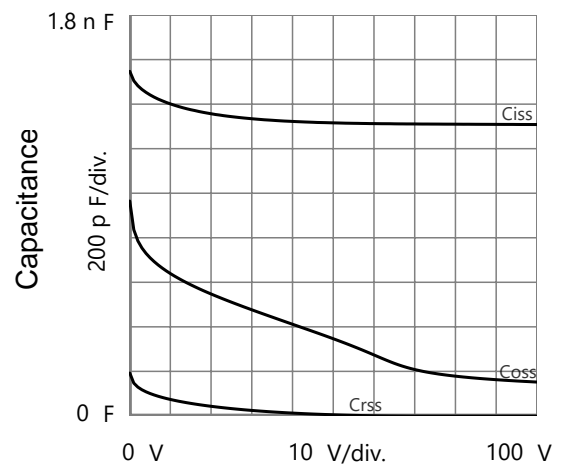
**Gate to Source Voltage
Drain to Source Resistance vs. Gate to Source Voltage**



**Drain Current
Drain to Source Resistance vs. Drain Current**

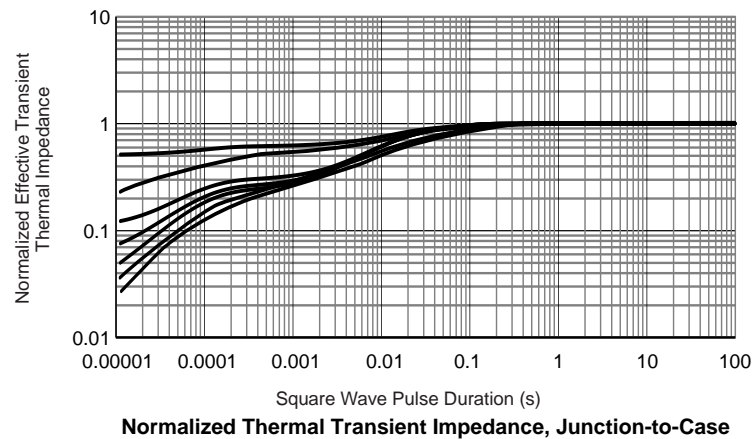
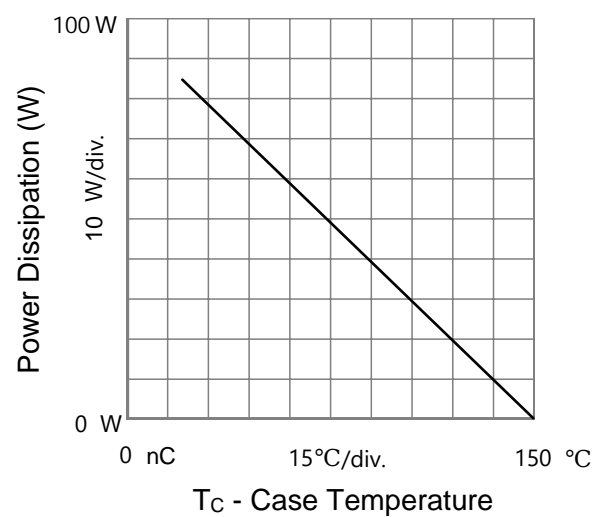
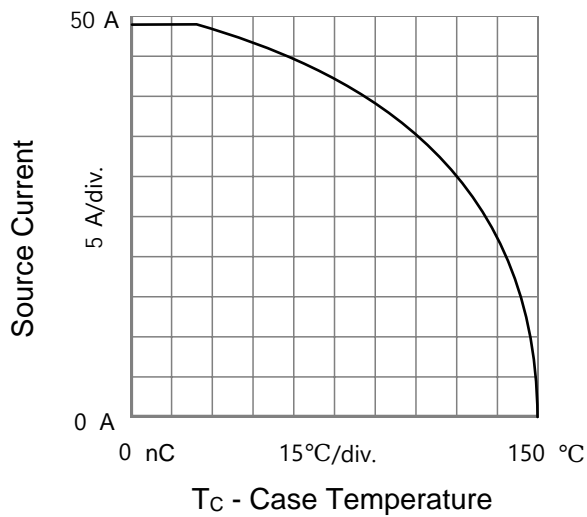
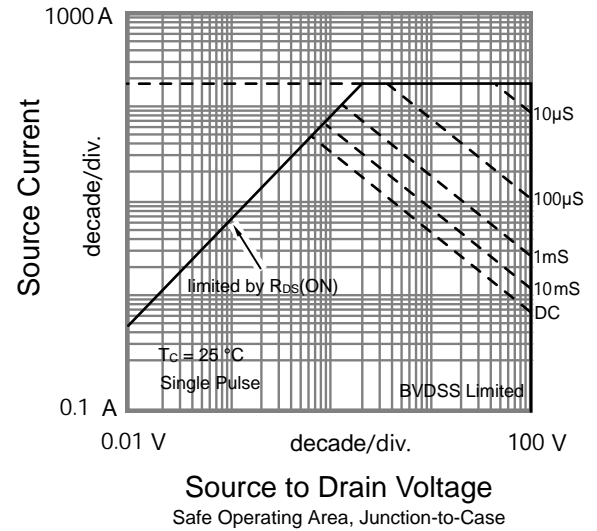
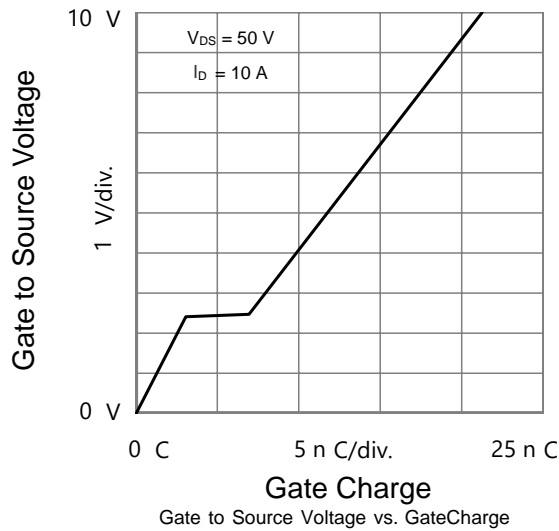


**Source to Drain Voltage
Body Diode Forward Characteristics**

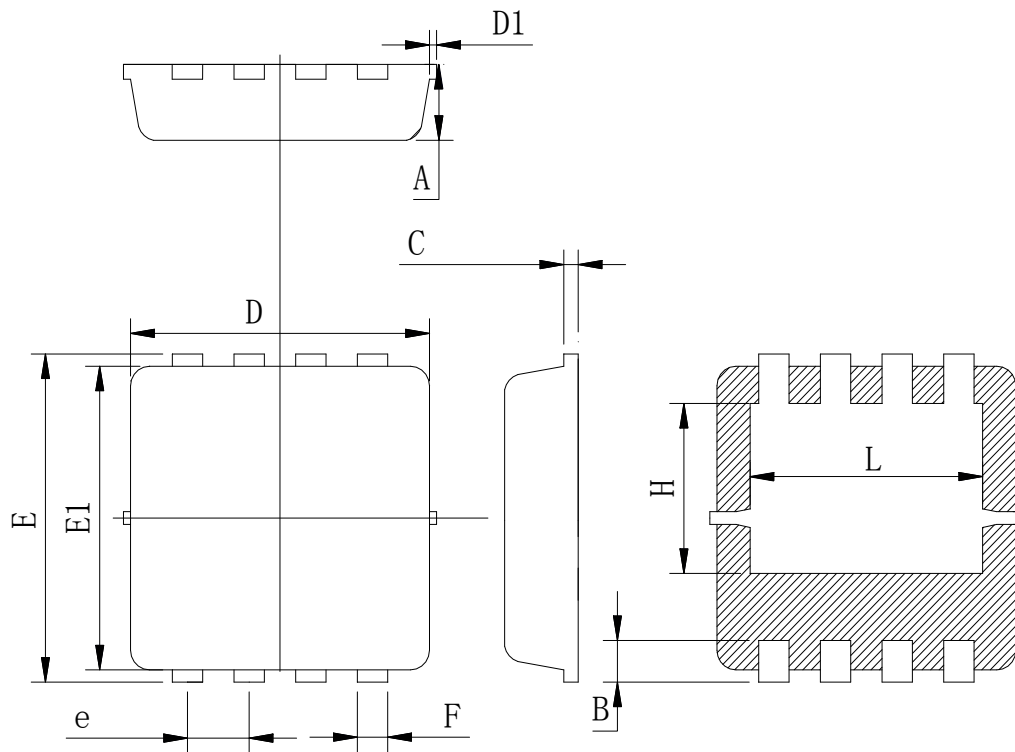


**Drain to Source Voltage
Capacitances**

TYPICAL CHARACTERISTICS ($T_C = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)



PDFN 3.3X3.3 PACKAGE OUTLINE



COMMON DIMENSIONS
(UNITS OF MEASURE=MILLIMETER)

Symbol	Min	Typ	Max
A	0.600	0.775	1.000
B	0.20	0.38	0.55
C	0.05	0.15	0.40
D	3.10	3.25	3.50
D1	-	-	0.15
E	3.15	3.35	3.50
E1	2.60	3.10	3.45
e	0.50	0.65	0.80
F	0.15	0.32	0.45
H	1.25	1.73	2.10
L	2.20	2.45	2.85

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